

ABSTRACT OF THE DISCLOSURE

An object of the present invention is to provide an apparatus and method for determining a size of a bonding film for bonding a bonding target having a size which varies due to temperature variation, at an environmental temperature which is different from a temperature during use. The method includes the steps of: measuring an actual size of the bonding portion of the circuit electrode at the first temperature; comparing the actual size of the bonding portion with a designed size of the bonding portion at the first temperature; and determining a cutting size of the bonding material based on a comparison result and mounting the bonding material over the bonding portion.